

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.33365	100.0	4.8
<b>Subtotal</b>				<b>0.33365</b>	<b>100</b>	<b>4.8</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02787	100.0	0.40092
	Pure metal	Aluminium (Al)	7429-90-5	0.15848	100.0	2.28
	Pure metal	Aluminium (Al)	7429-90-5	0.02787	100.0	0.40092
<b>Subtotal</b>				<b>0.21422</b>	<b>300</b>	<b>3.08184</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73776	100.0	25
<b>Subtotal</b>				<b>1.73776</b>	<b>100</b>	<b>25</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02336	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05839	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.30706	99.86	838.824
<b>Subtotal</b>				<b>58.38881</b>	<b>100</b>	<b>840</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.40167	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.25594	16.0	90
	Filler	Silica fused	60676-86-0	29.32474	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.1173	0.3	1.6875
<b>Subtotal</b>				<b>39.09965</b>	<b>100</b>	<b>562.5</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.0113	5.0	0.1625
	Lead alloy	Silver (Ag)	7440-22-4	0.00565	2.5	0.08125
	Lead alloy	Lead (Pb)	7439-92-1	0.20897	92.5	3.00625
<b>Subtotal</b>				<b>0.22592</b>	<b>100</b>	<b>3.25</b>
<b>Total</b>				<b>100.00001</b>	<b>100</b>	<b>1438.63184</b>

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